

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1339csw#trpbf

(Engineering Calculation)

SOIC WIDE

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**TOTAL MASS (g) : 0.543881**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.006038	1000000	11101.6992188		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.153163	975000	281611.375		
		Iron (Fe)	7439-89-6	0.003770	24000	6931.66699219		
		Phosphorus (P)	7723-14-0	0.000047	300	86.4160079956		
		Zinc (Zn)	7440-66-6	0.000110	700	202.250228882		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.157090</b>	<b>1000000</b>	<b>288831.71875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.005974	1000000	10983.4326172		
		<b>External Plating Total:</b>				<b>0.005974</b>	<b>1000000</b>	<b>10983.4326172</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001257	1000000	2311.16870117		
<b>Internal Plating Total:</b>				<b>0.001257</b>	<b>1000000</b>	<b>2311.16870117</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001482	750000	2724.86230469		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000494	250000	908.287353516		
<b>Die Attach Total:</b>				<b>0.001976</b>	<b>1000000</b>	<b>3633.14941406</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.038213	103000	70259.890625		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.332045	895000	610510.6875		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000742	2000	1364.26977539		
		<b>Encapsulation Total:</b>				<b>0.371000</b>	<b>1000000</b>	<b>682134.875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000546	1000000	1003.89672852		
					<b>TOTAL MASS (g) :</b>	<b>0.543881</b>		